

Abstract of the Disclosure

A package for accommodating electronic parts intended for inhibiting the variation of the characteristic impedance of signal lines, electrical coupling
5 between signal lines, crosstalk noise, and ground bounce, and a method for manufacturing such a semiconductor device and package. In a case-type BGA using a buildup substrate 2, the buildup substrate 2 and a stiffener 3 are adhered with a conductive adhesive layer 27 using a conductive adhesive, and a grounding plane 12 is constituted using said stiffener 3 and said buildup
10 substrate 2.

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